MPC303X-4L,MPC304X-4L, MPC306X-4L,MPC308X-4L Series

DIP4, DC Input, Zero-Corss Photo TRIAC Optocoupler

■ Features

- High isolation 5000 VRMS
- DC input with zero-cross photo triac output
- Operating temperature range - 40 °C to 100 °C
- RoHS & REACH Compliance
- Halogen free
- MSL class 1
- Regulatory Approvals
  - UL - UL1577
  - VDE - EN60747-5-5(VDE0884-5)
  - CQC – GB4943.1, GB8898

■ Applications

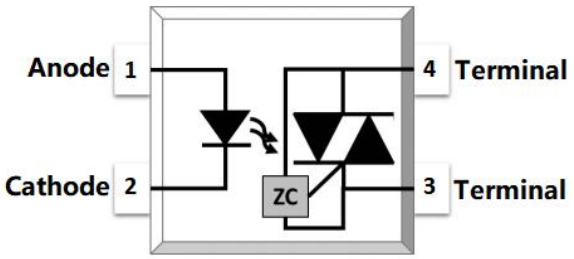
- Solenoid/valve controls
- Lighting controls
- Motor controls
- Temperature controls
- Static AC power switches
- Solid state relays
- Interfacing microprocessors to 115 to 240VAC peripherals

■ Description

The MPC303X-4L, MPC304X-4L and MPC306X-4L, MPC308X-4L series combine an AlGaAs infrared emitting diode as the emitter which is optically coupled to a monolithic silicon zero-cross photo triac in a plastic DIP4 package with different lead forming options.

With the robust coplanar double mold structure, MPC303X-4L, MPC304X-4L and MPC 306X-4L,MPC308X-4L series provide the most stable isolation feature.

■ Schematic



ABSOLUTE MAXIMUM RATINGS					
PARAMETER		SYMBOL	VALUE	UNIT	NOTE
INPUT					
Forward Current		I_F	60	mA	
Reverse Voltage		V_R	6	V	
Junction Temperature		Tj	125	°C	
Input Power Dissipation		P_I	100	mW	
OUTPUT					
Off-state Output Terminal Voltage	MPC303X-4L	V_{DRM}	250	V	
	MPC304X-4L		400		
	MPC306X-4L		600		
	MPC308X-4L		800		
Peak Repetitive Surge Current PW=100μs, 120pps		I_{TSM}	1	A	
On-State RMS Current		$I_{T(RMS)}$	100	mA	
Junction Temperature		Tj	125	°C	
Output Power Dissipation		P_O	300	mW	
COMMON					
Total Power Dissipation		Ptot	400	mW	
Isolation Voltage		Viso	5000	Vrms	1
Operating Temperature		Topr	-40~100	°C	
Storage Temperature		Tstg	-55~150	°C	
Soldering Temperature		Tsol	260	°C	2

Note 1. AC For 1 Minute, R.H. = 40 ~ 60%

Note 2. For 10 seconds

ELECTRICAL OPTICAL CHARACTERISTICS at Ta=25°C							
PARAMETER	SYMBOL	MIN.	TYP.	MAX.	UNIT	TEST CONDITION	NOTE
INPUT							
Forward Voltage	V_F	-	1.24	1.4	V	I_F=10mA	
Reverse Current	I_R	-	-	10	μA	V_R=6V	
Input Capacitance	Cin	-	8.5	250	pF	V=0, f=1kHz	
OUTPUT							
Peak Off-state Current, Either Direction	I_{DRM}	-	-	100	nA	V_{DRM}=Rated V_{DRM} I_F=0	3
Peak On-state Current, Either Direction	V_{TM}	-	1.59	2.5	V	I_{TM}=100mA	
Critical Rate of Rise of Off-state Voltage Breakdown Voltage	dV/dt	1000	-	-	V	V_{PEAK} =Rated V_{DRM}	4
TRANSFER CHARACTERISTICS							
LED Trigger Current	MPC3031-4L,MPC3041-4L, MPC3061-4L,MPC3081-4L	I_{FT}	-	-	15	mA	Terminal Voltage = 3V I_{TM}=100mA
	MPC3032-4L,MPC3042-4L, MPC3062-4L,MPC3082-4L		-	-	10		
	MPC3032-4L,MPC3043-4L, MPC3063-4L,MPC3083-4L		-	-	5		
Holding Current Saturation Voltage		I_H	-	237	-	μA	
Isolation Resistance		Riso	10^12	10^14	-	Ω	DC500V, 40 ~ 60% R.H.
Floating Capacitance		C_{IO}	-	0.4	1	pF	V=0, f=1MHz
ZERO-CROSS CHARACTERISTICS							
Inhibit Voltage		V_{INH}	-	-	20	V	I_F=Rated I_{FT}
Leakage in Inhibited State		I_{DRM2}	-	-	500	μA	I_F=Rated I_{FT} V_{DRM}=Rated V_{DRM}

Note3. Test voltage must be applied within dV/dt rating.

Note4. Refer to Fig.17 & Fig.18.

CHARACTERISTIC CURVES

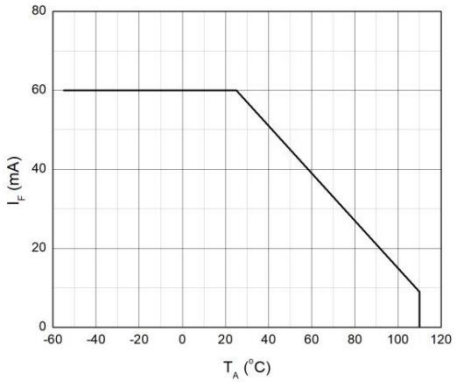


Fig.1 Forward Current vs. Ambient Temperature

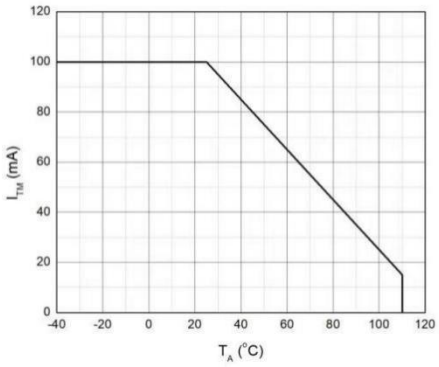


Fig.2 On-state Terminal Current vs. Ambient Temperature

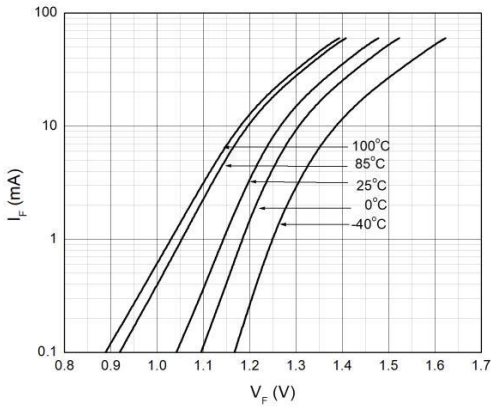


Fig.3 Forward Current vs. Forward Voltage

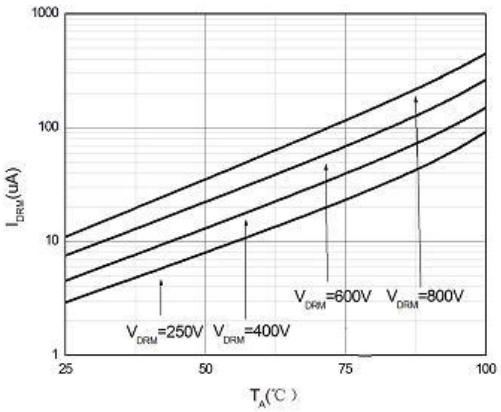


Fig.4 Off-state Terminal Current vs. Ambient Temperature

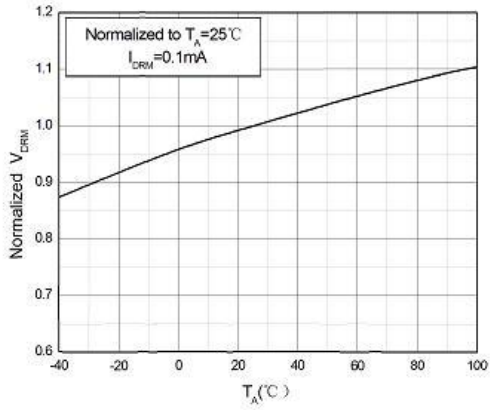


Fig.5 Normalized Off-state Terminal Voltage vs. Ambient Temperature

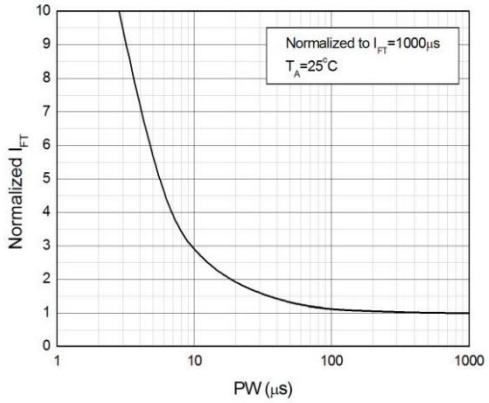


Fig.6 Normalized Trigger Current vs. LED Trigger Pulse Width

CHARACTERISTIC CURVES

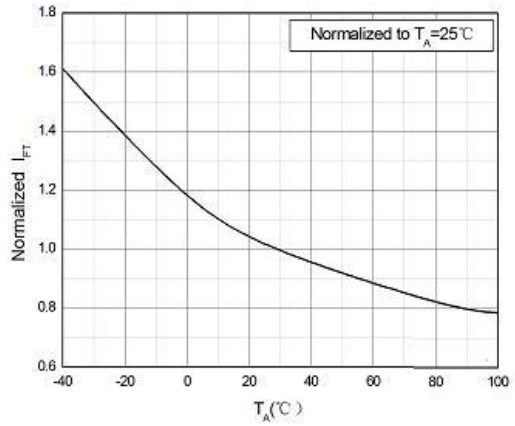


Fig.7 Normalized Trigger Current vs. Ambient Temperature

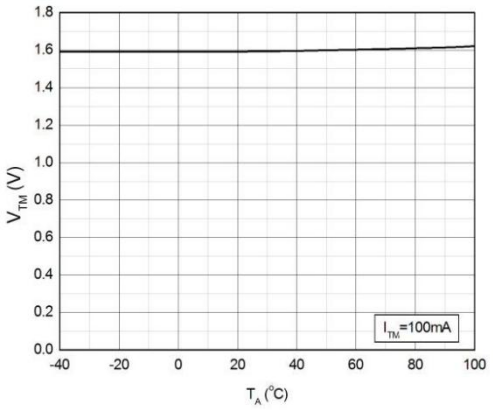


Fig.8 On-state Terminal Voltage vs. Ambient Temperature

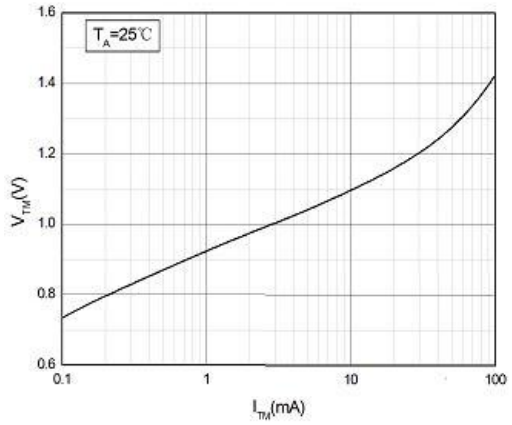


Fig.9 On-state Terminal Voltage vs. On-state Terminal Current

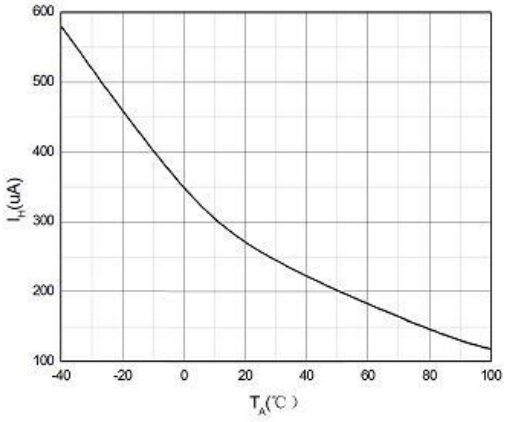


Fig.10 Holding Current vs. Ambient Temperature

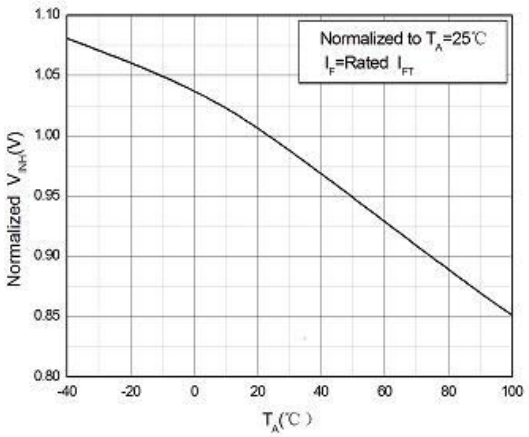


Fig.11 Normalized Inhibit Voltage vs. Ambient Temperature

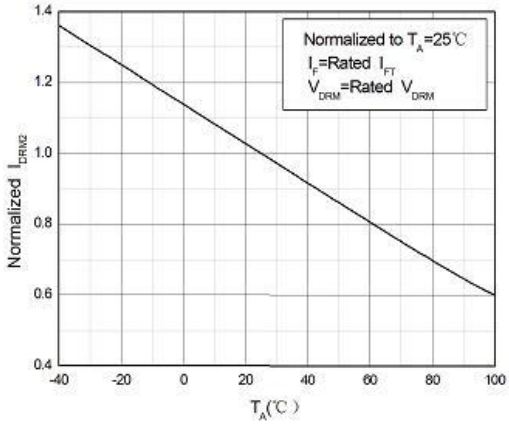


Fig.12 Normalized Leakage in Inhibit State vs. Ambient Temperature

CHARACTERISTIC CURVES

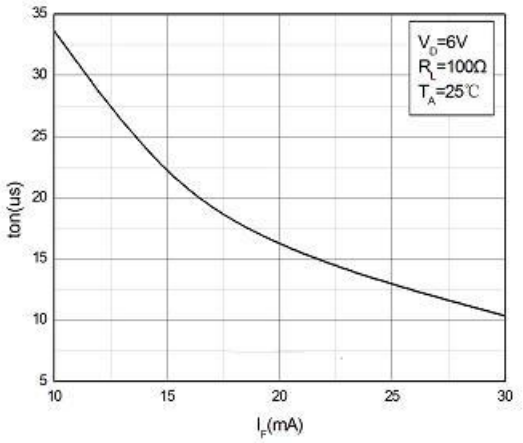


Fig.13 Turn On Time vs. Forward Current

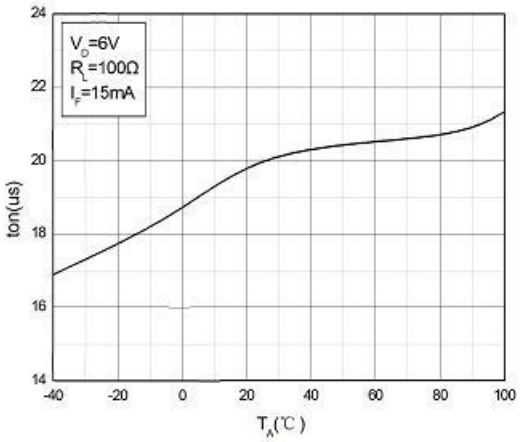


Fig.14 Turn On Time vs. Ambient Temperature

TEST CIRCUITS

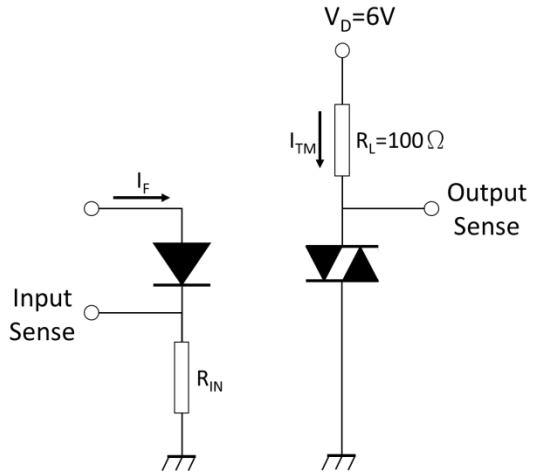


Fig.15 Test Circuits of Turn On Time

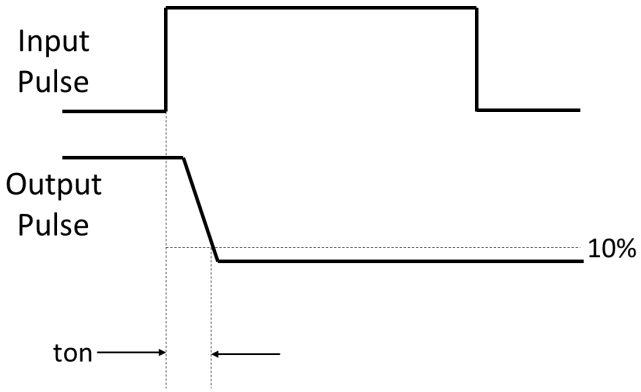


Fig.16 Waveforms of Turn On Time

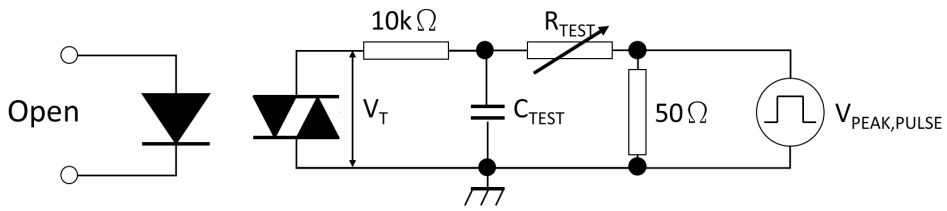
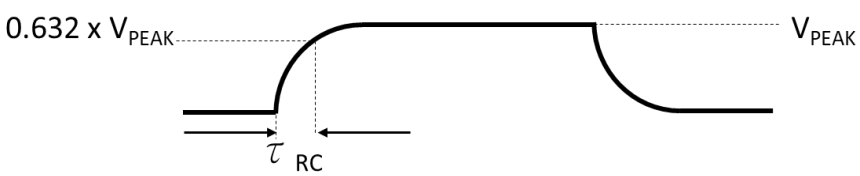


Fig.17 Test Circuits of dV/dt

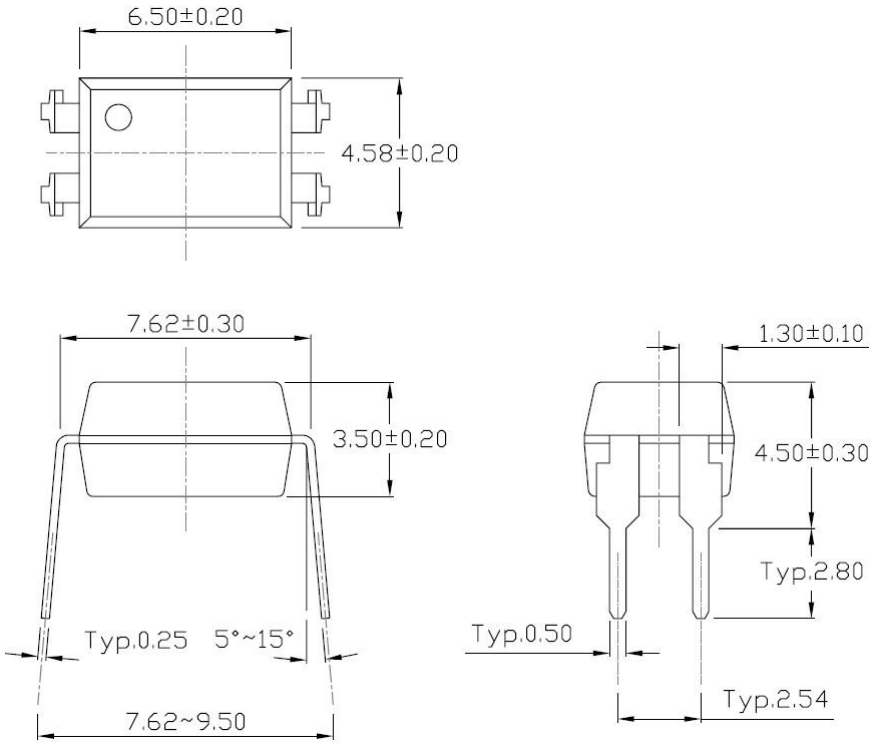


$$dv/dt = \frac{0.632 \times V_{PEAK}}{\tau_{RC}}$$

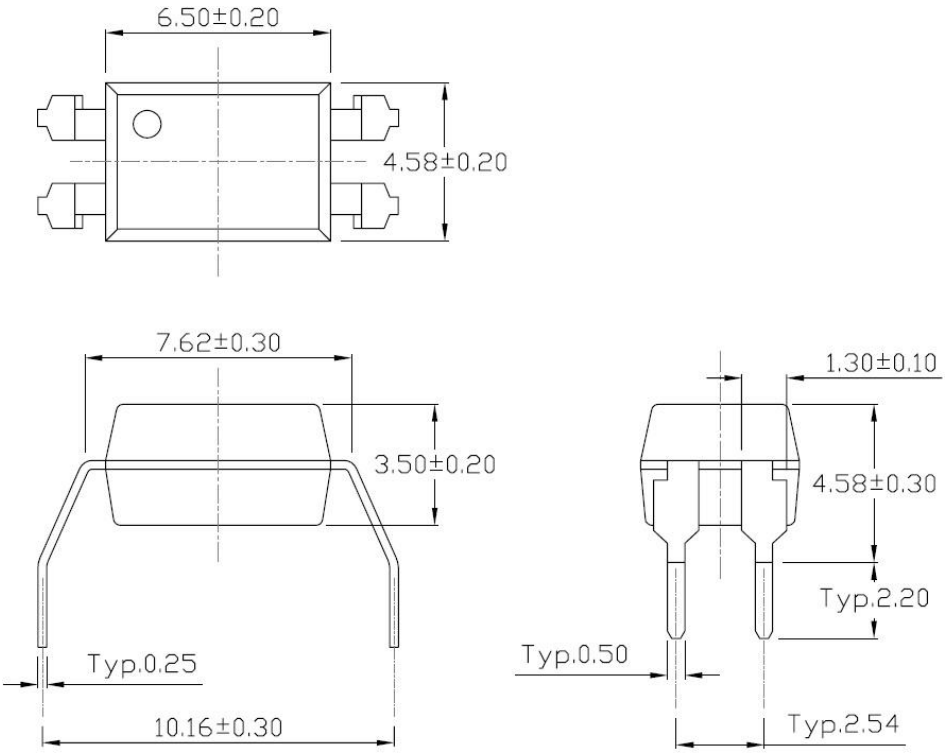
Fig.18 Waveforms of dV/dt

PACKAGE DIMENSIONS (Dimensions in mm unless otherwise stated)

Standard DIP – Through Hole (DIP Type)

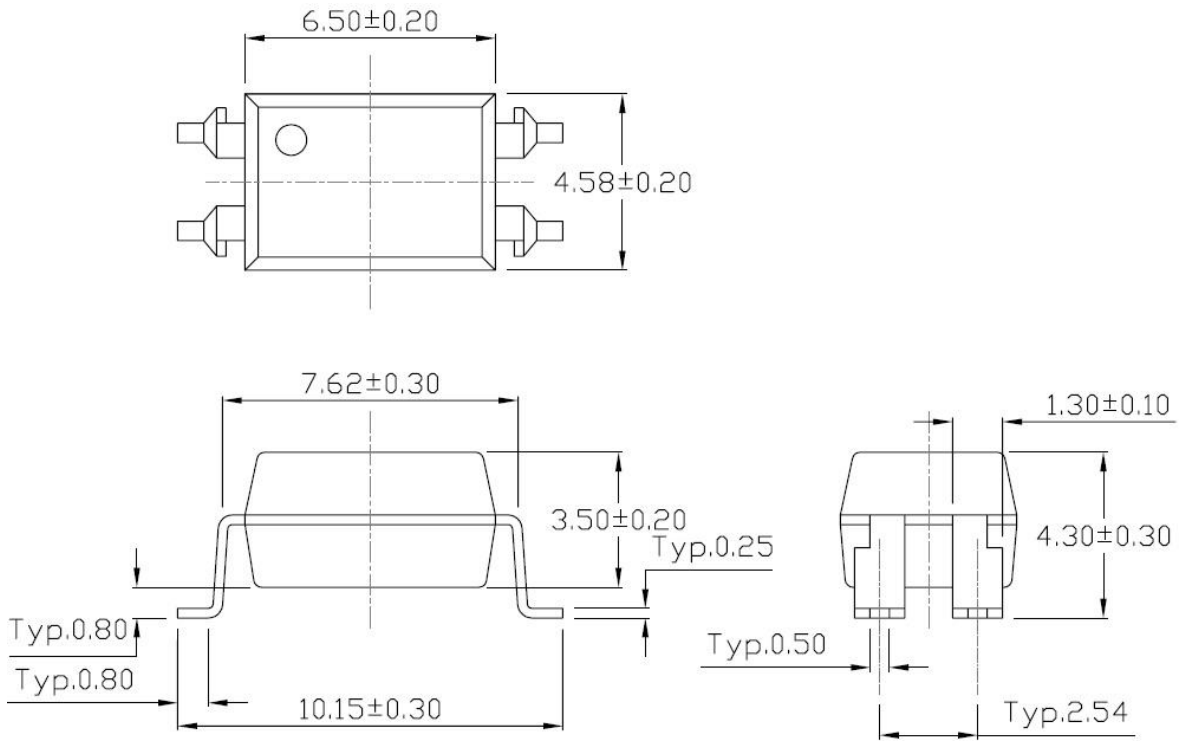


Gullwing (400mil) Lead Forming – Through Hole (M Type)

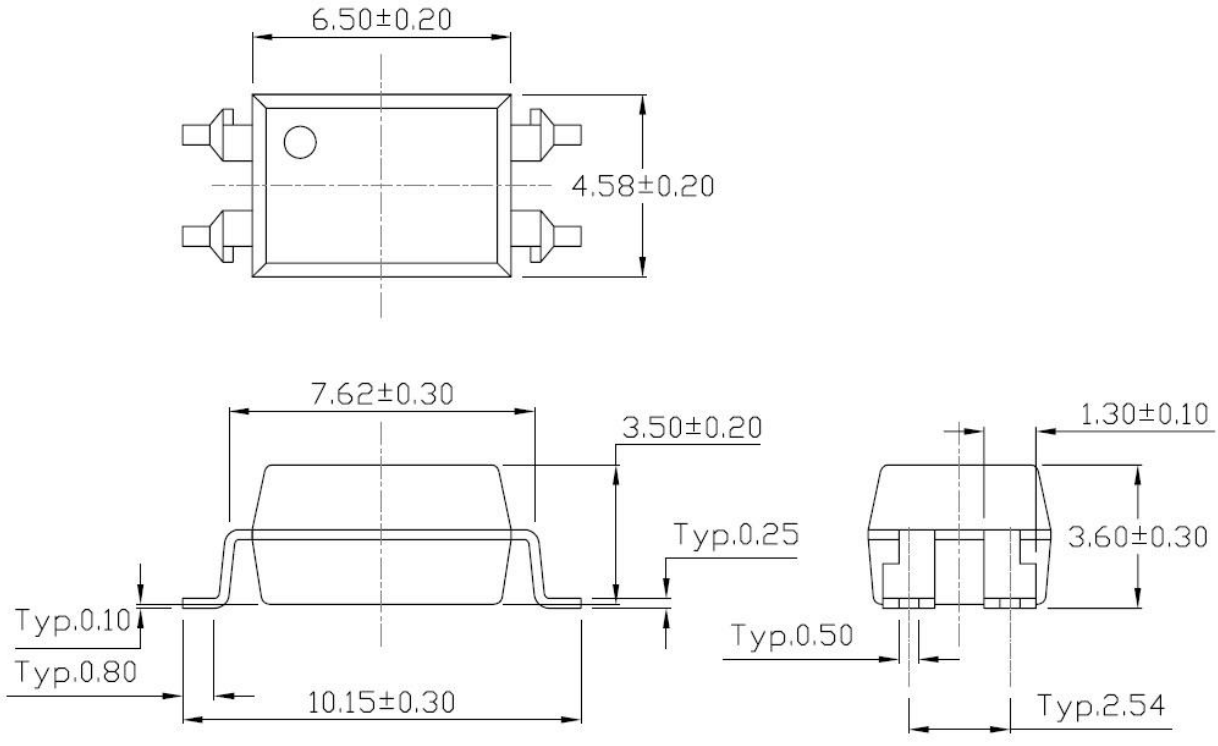


PACKAGE DIMENSIONS (Dimensions in mm unless otherwise stated)

Surface Mount Lead Forming (S Type)

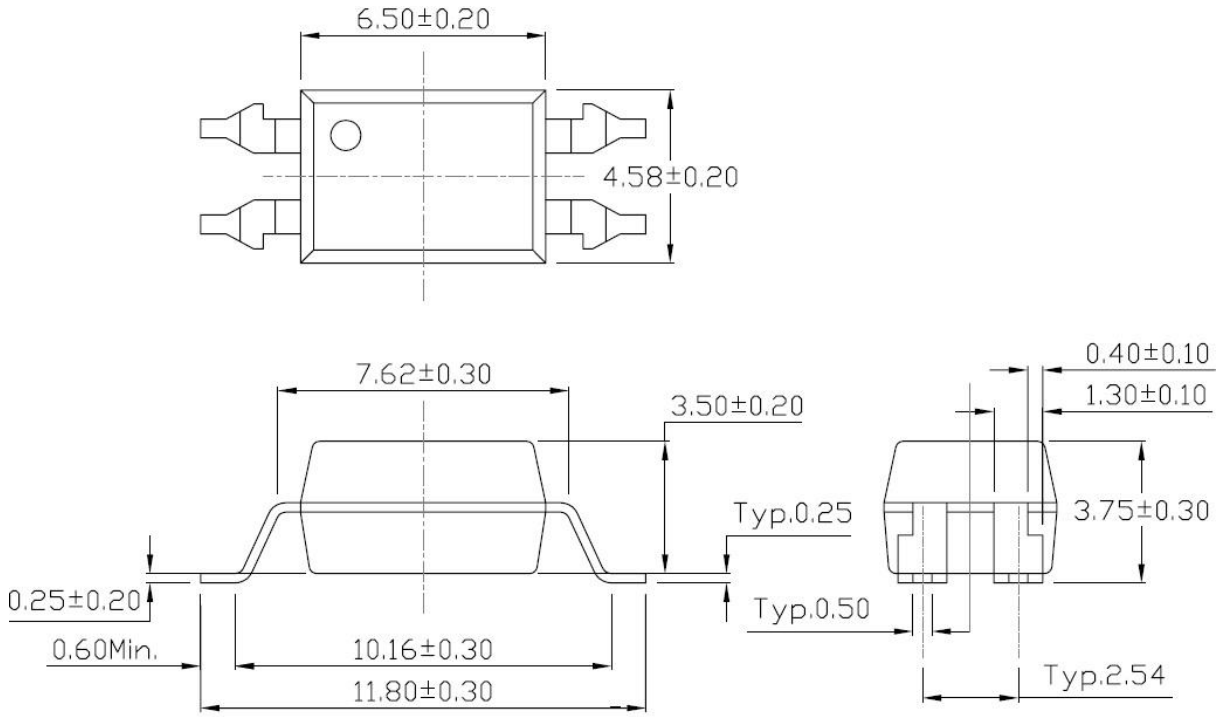


Surface Mount (Low Profile) Lead Forming (SL Type)



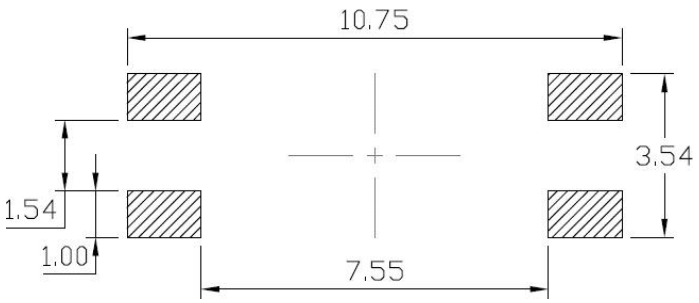
PACKAGE DIMENSIONS (Dimensions in mm unless otherwise stated)

Surface Mount (Gullwing) Lead Forming (SLM Type)

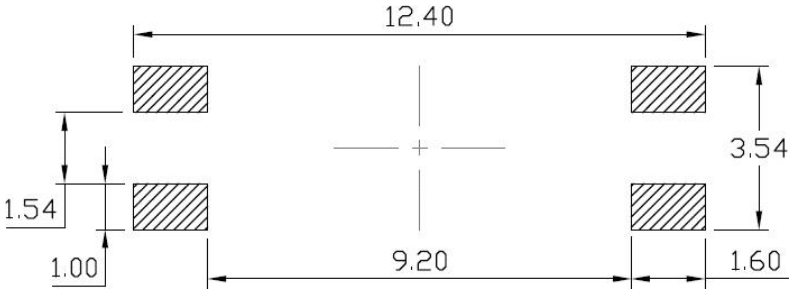


RECOMMENDED SOLDER MASK (Dimensions in mm unless otherwise stated)

Surface Mount Lead Forming & Surface Mount (Low Profile) Lead Forming

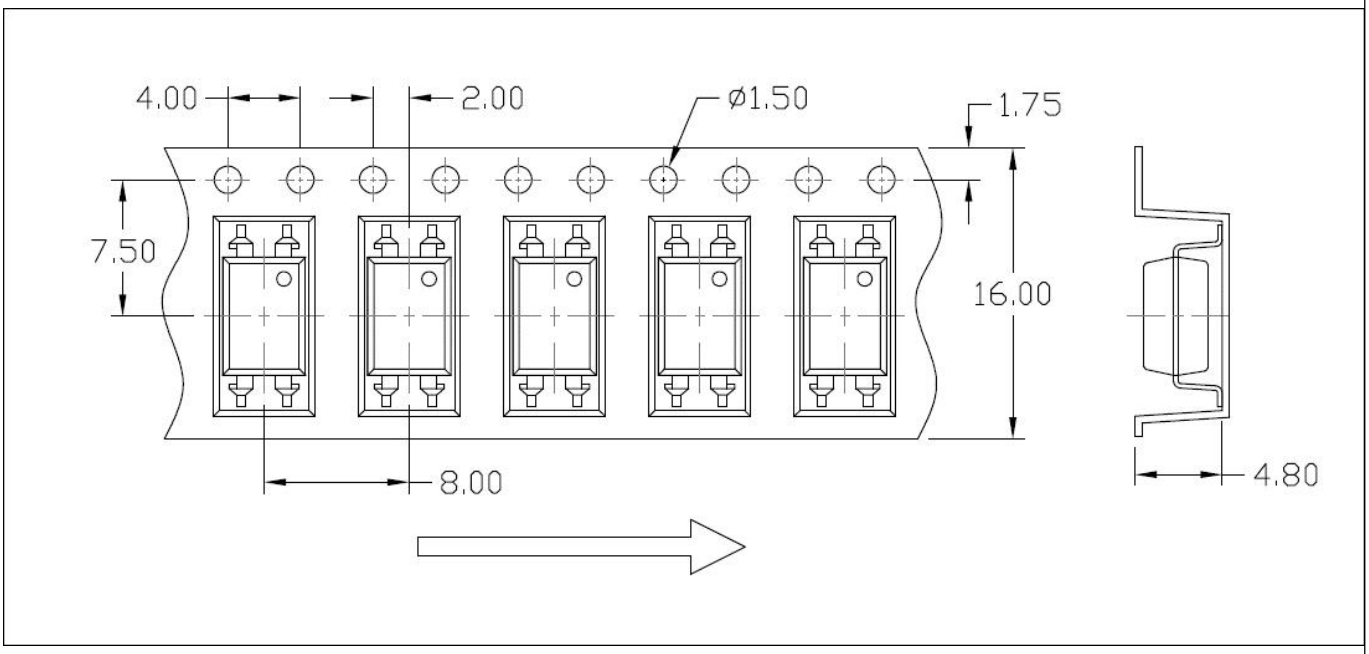


Surface Mount (Gullwing) Lead Forming

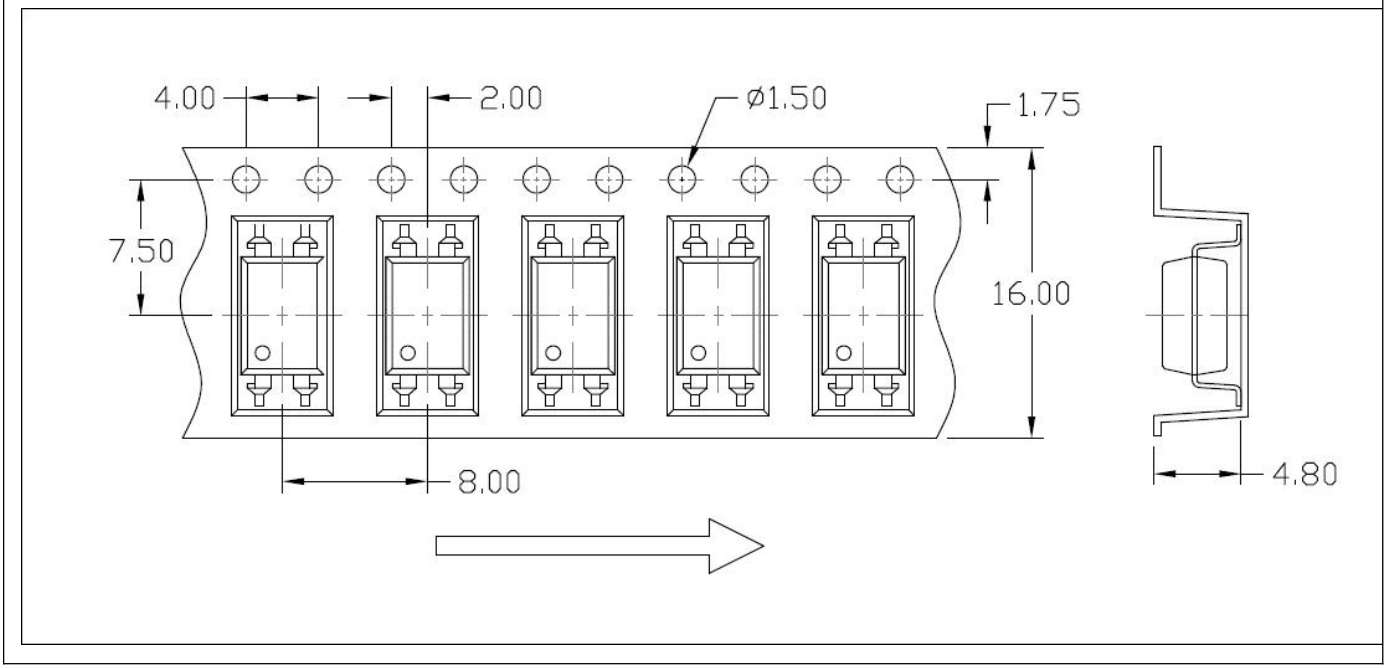


CARRIER TAPE SPECIFICATIONS (Dimensions in mm unless otherwise stated)

Option S(T1) & SL(T1)

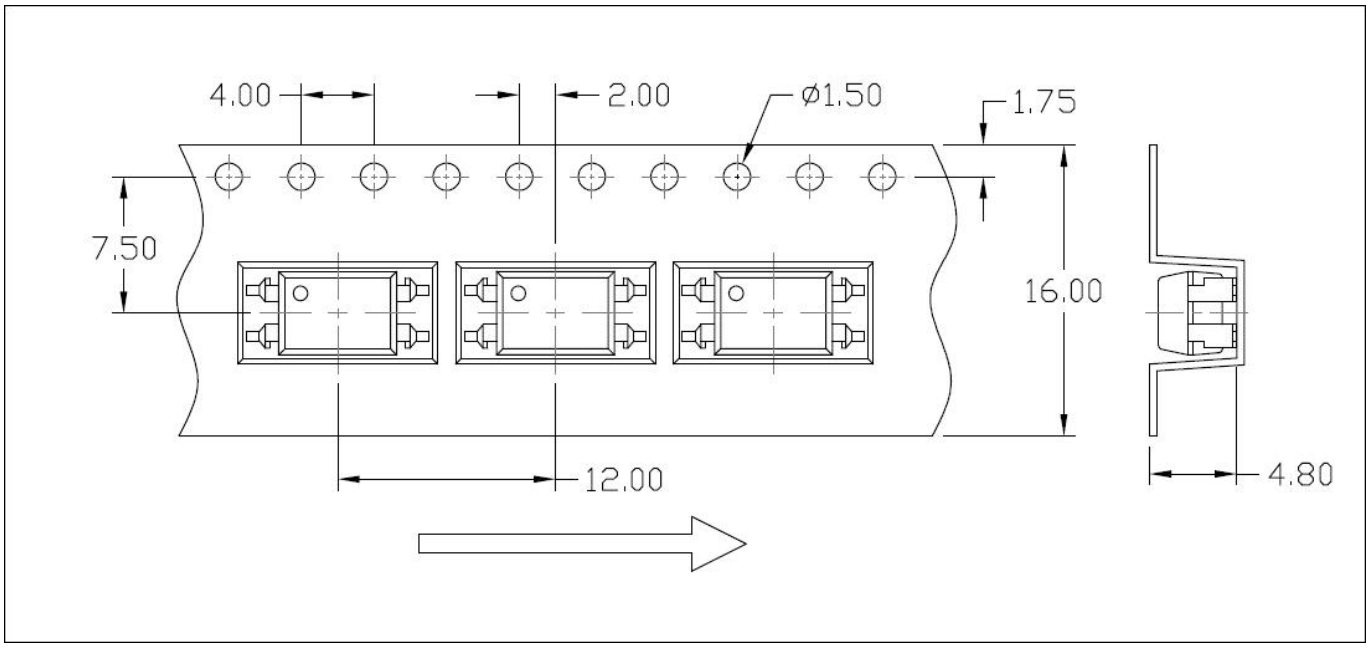


Option S(T2) & SL(T2)

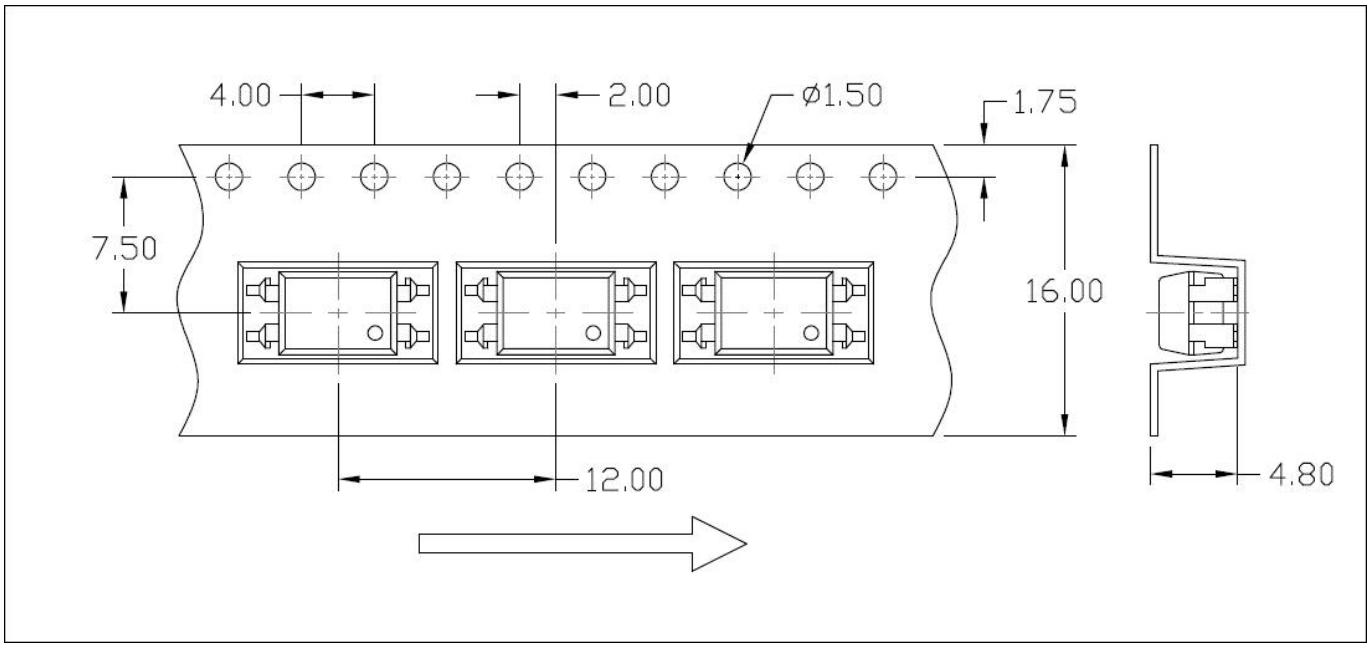


CARRIER TAPE SPECIFICATIONS (Dimensions in mm unless otherwise stated)

Option S(T3) & SL(T3)

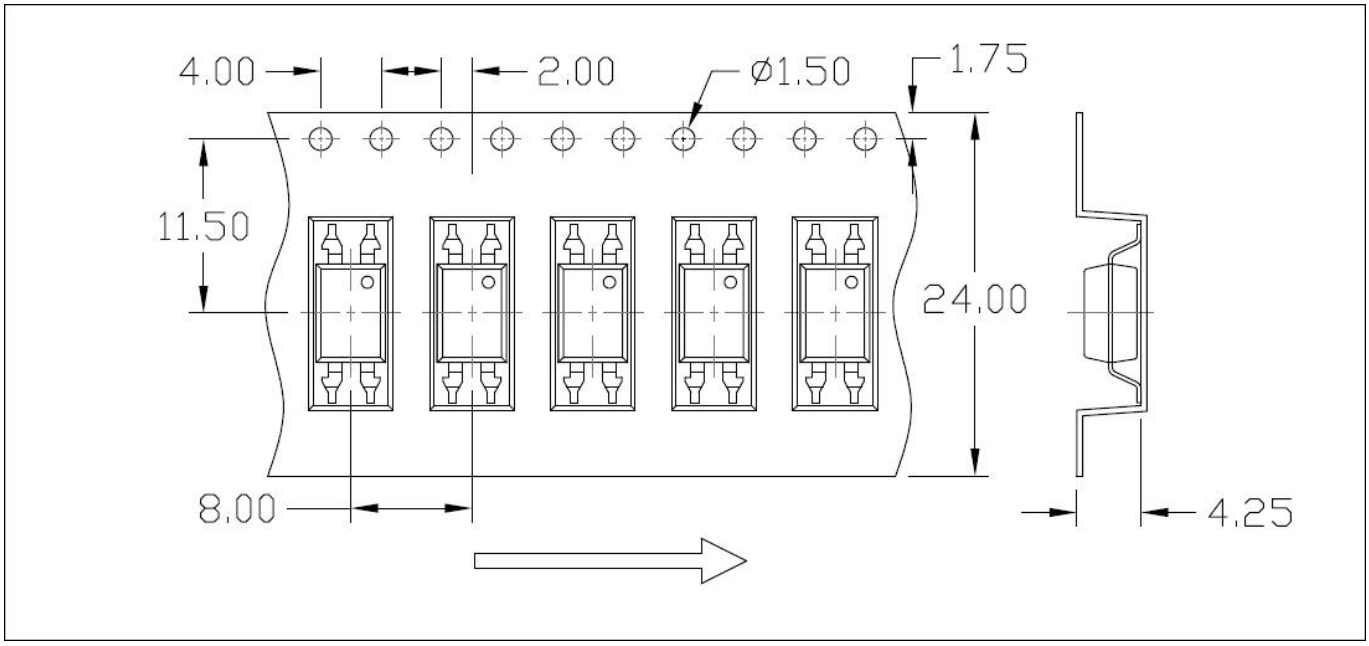


Option S(T4) & SL(T4)

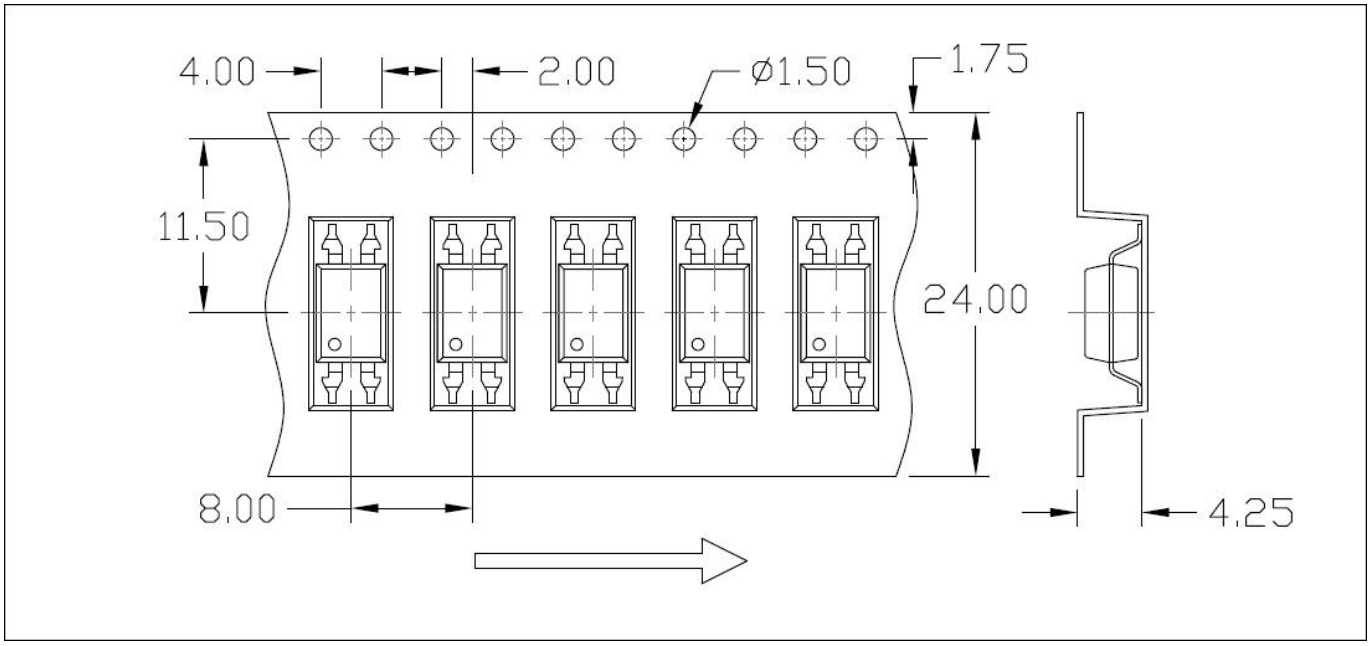


CARRIER TAPE SPECIFICATIONS (Dimensions in mm unless otherwise stated)

Option SLM(T1)

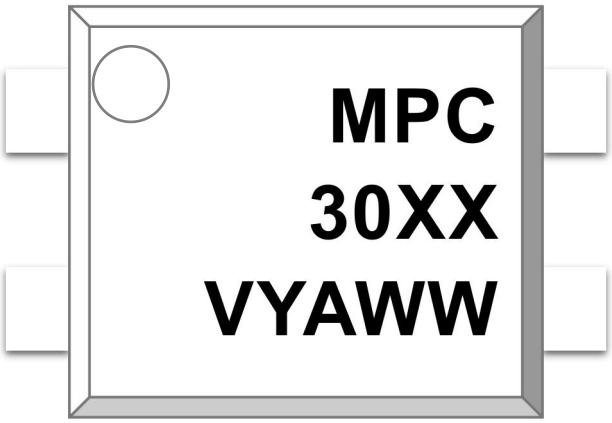


Option SLM(T2)



ORDERING AND MARKING INFORMATION

MARKING INFORMATION



MPC	**: Company Abbr.**
30XX	**: Part Number&Rank**
V	**: VDE Option**
Y	**: Fiscal Year**
A	**: Manufacturing Code**
WW	**: Work Week**

ORDERING INFORMATION

MPC30XX-4L(Y)(Z)-GV

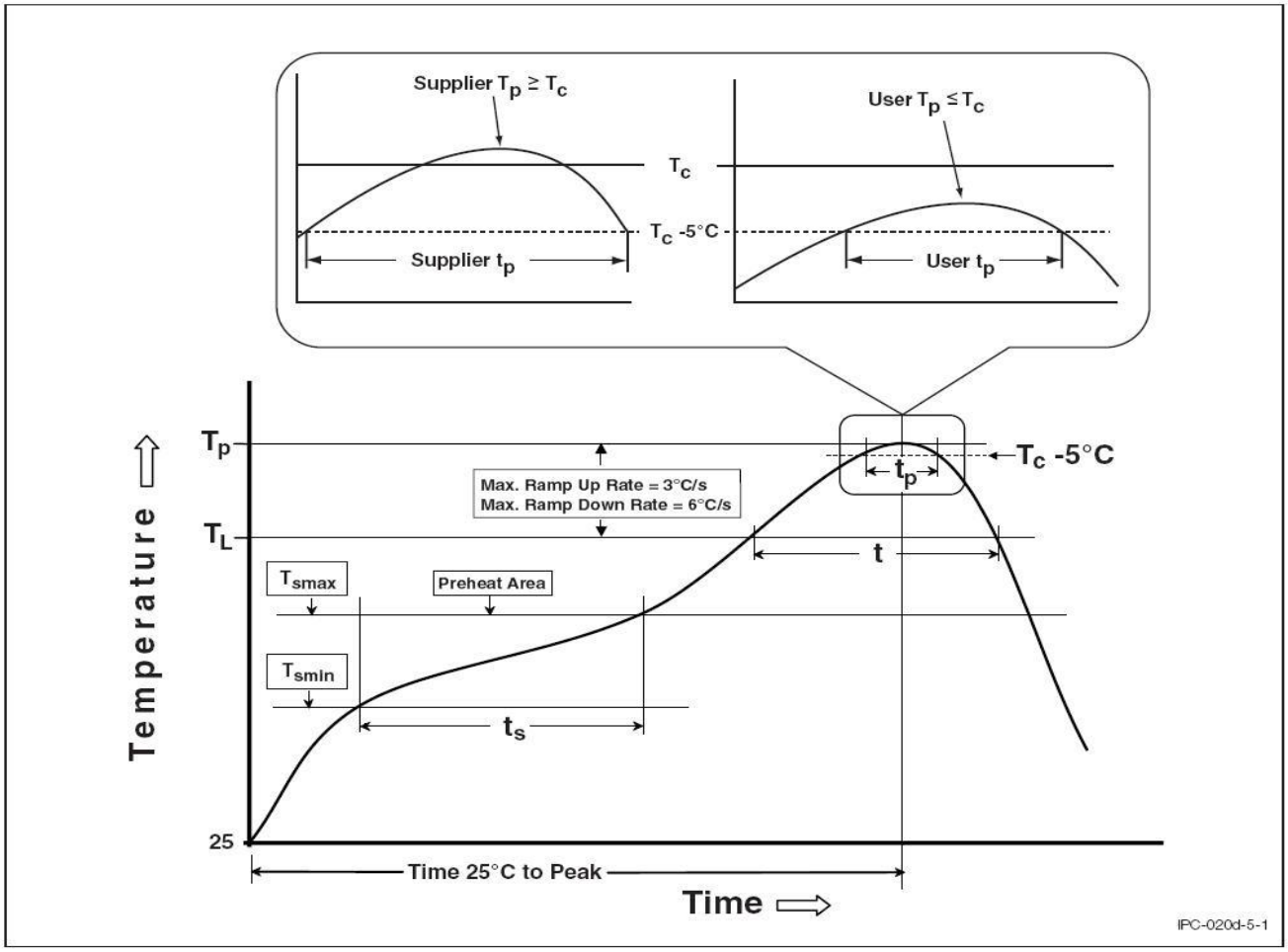
MPC – Company Abbr. 30XX –Part Number&Rank (31/32/33/41/42/43/61/62/63 /81/82/83)	Y – Lead Form Option (M/S/SL/SLM/None) Z – Tape and Reel Option (T1/T2/T3/T4) G – Green V – VDE Option (V or None)

PACKING QUANTITY

Option	Description	Quantity
None	Standard 4 Pin Dip	100 Units/Tube
M	Gullwing (400mil) Lead Forming	100 Units/Tube
S(T1)	Surface Mount Lead Forming – With Option 1 Taping	1500 Units/Reel
S(T2)	Surface Mount Lead Forming – With Option 2 Taping	1500 Units/Reel
S(T3)	Surface Mount Lead Forming – With Option 3 Taping	1000 Units/Reel
S(T4)	Surface Mount Lead Forming – With Option 4 Taping	1000Units/Reel
SL(T1)	Surface Mount (Low Profile) Lead Forming– With Option 1 Taping	1500 Units/Reel
SL(T2)	Surface Mount (Low Profile) Lead Forming – With Option 2 Taping	1500 Units/Reel
SL(T3)	Surface Mount (Low Profile) Lead Forming– With Option 3 Taping	1000 Units/Reel
SL(T4)	Surface Mount (Low Profile) Lead Forming – With Option 4 Taping	1000 Units/Reel
SLM(T1)	Surface Mount (Gullwing) Lead Forming– With Option 1 Taping	1500 Units/Reel
SLM(T2)	Surface Mount (Gullwing) Lead Forming – With Option 2 Taping	1500 Units/Reel

REFLOW INFORMATION

REFLOW PROFILE



Profile Feature	Sn-Pb Assembly Profile	Pb-Free Assembly Profile
Temperature Min. (Tsmin)	100	150°C
Temperature Max. (Tsmax)	150	200°C
Time (ts) from (Tsmin to Tsmax)	60-120 seconds	60-120 seconds
Ramp-up Rate (tL to tP)	3°C/second max.	3°C/second max.
Liquidous Temperature (TL)	183°C	217°C
Time (tL) Maintained Above (TL)	60 – 150 seconds	60 – 150 seconds
Peak Body Package Temperature	235°C +0°C / -5°C	260°C +0°C / -5°C
Time (tP) within 5°C of 260°C	20 seconds	30 seconds
Ramp-down Rate (TP to TL)	6°C/second max	6°C/second max
Time 25°C to Peak Temperature	6 minutes max.	8 minutes max.

DISCLAIMER

- Our company is continually improving the quality, reliability, function and design. Our company reserves the right to make changes without further notices.
- The characteristic curves shown in this datasheet are representing typical performance which are not guaranteed.
- This product is not intended to be used for military, aircraft, automotive, medical, life sustaining or lifesaving applications or any other application which can result in human injury or death.
- Immerge unit's body in solder paste is not recommended.
- Discoloration might be occurred on the package surface after soldering, reflow or long-time use. It neither impacts the performance nor reliability.

■ Revision History

Version	Date	Subjects (major changes since last revision)
1.0	2018-12-21	Datasheet Complete